

# Schottky Barrier Rectifier, Trench-based, High Performance

## NRTS6100PFS, NRVTS6100PFS

This Trench Schottky rectifier is a high performance device in a TO-277 package. The lower forward voltage, less leakage current, and small junction capacitance are suitable to high switching frequency high density DC to DC conversion applications. It offers higher avalanche energy capability for Oring or reverse protection applications. The TO-277 package provides excellent thermal performance, less land area of board space, and a low profile.

#### **Features**

- Lower Forward Voltage Drop
- Less Leakage Current in High Temperature
- Small Junction Capacitance for High Switching Frequency
- Higher Avalanche Energy Capability
- 175°C Operating Junction Temperature
- Package Provided Capability of Inspection and Probe After Board Mounting
- Good Alternative Solution of SMC and DPAK Package

#### **Mechanical Characteristics:**

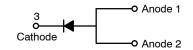
- Case: Epoxy, Molded
- Epoxy Meets Flammability Rating UL 94-0 @ 0.125 in.
- Lead Finish: 100% Matte Sn (Tin)
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Device Meets MSL 1 Requirements
- ESD Ratings:
  - Human Body Model: ≥ 8000 V (Class 3B)
  - ◆ Charged Device Model: > 1000 V (Class C5)

## **Applications**

- High Switching Frequency DC/DC Converters
- 2<sup>nd</sup> Rectifier
- Oring / Reverse Protection
- Freewheeling Diode for Inductive Loads

## SCHOTTKY BARRIER RECTIFIER, 6 AMPERES 100 VOLTS





### **MARKING DIAGRAM**

T06100 AWLYW

T06100 = Specific Device Code
A = Assembly Location
Y = Year
W = Work Week
WI = Wafer Lot

#### ORDERING INFORMATION

Device	Package	Shipping†
NRTS6100PFST3G	TO-277 (Pb-Free)	1500 / Tape & Reel
NRVTS6100PFST3G	TO-277 (Pb-Free)	1500 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	100	V
Continuous Forward Current (T <sub>C</sub> = 168°C, DC)	I <sub>F(DC)</sub>	6	Α
Peak Repetitive Forward Current, (T <sub>C</sub> = 166°C, Square Wave, Duty = 0.5)	I <sub>FRM</sub>	12	Α
Non-Repetitive Avalanche Energy (T <sub>J</sub> = 25°C)	E <sub>AS</sub>	145	mJ
Storage Temperature Range	T <sub>stg</sub>	-65 to +175	°C
Operating Junction Temperature (Note 1)	TJ	−55 to +175	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

## THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	70	°C/W
Thermal Resistance, Junction-to-Case Bottom	$R_{\theta JCB}$	2.2	°C/W
Thermal Characterization, Junction-to-Case Top	$\Psi_{JCT}$	1.1	°C/W
Thermal Characterization, Junction-to-Lead of Cathode	$\Psi_{JLC}$	0.7	°C/W

NOTE: (Assumes 600 mm<sup>2</sup>, 1 oz. copper bond pad on a FR4 board)

### **ELECTRICAL CHARACTERISTICS**

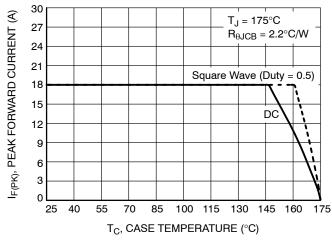
Characteristic	Symbol	Тур	Max	Unit
Instantaneous Forward Voltage (Note 2) $ \begin{aligned} (I_F = 3 \text{ A, } T_J = 25^\circ\text{C}) \\ (I_F = 3 \text{ A, } T_J = 125^\circ\text{C}) \\ (I_F = 6 \text{ A, } T_J = 25^\circ\text{C}) \\ (I_F = 6 \text{ A, } T_J = 125^\circ\text{C}) \end{aligned} $	V <sub>F</sub>	0.52 0.47 0.62 0.56	- - 0.68 0.62	>
Instantaneous Reverse Current (Note 2) (V <sub>R</sub> = Rated DC Voltage, T <sub>J</sub> = 25°C) (V <sub>R</sub> = Rated DC Voltage, T <sub>J</sub> = 125°C)	I <sub>R</sub>	6.2 3.3	50 15	μA mA
Junction Capacitance $(V_R = 1 \text{ V, } T_J = 25^{\circ}\text{C, } 1 \text{ MHz})$	CJ	827	-	pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

<sup>1.</sup> The heat generated must be less than the thermal conductivity from Junction-to-Ambient  $dP_D/dT_J < 1/R_{\theta JA}$ 

Pulse Test: Pulse Width = 300 μs, Duty Cycle ≤ 2.0%.

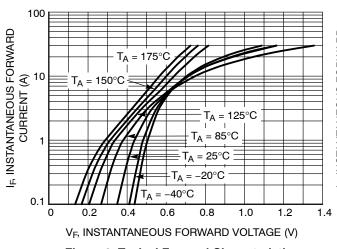
#### **TYPICAL CHARACTERISTICS**



20 I<sub>F(PK)</sub>, PEAK FORWARD CURRENT (A) T<sub>J</sub> = 175°C 18  $R_{\theta JA} = 70^{\circ}C/W$ 16 D = 0.2Square Wave 14 12 D = 0.310 D = 0.58 6 DC 4 25 40 85 100 115 130 145 TA, AMBIENT TEMPERATURE (°C)

Figure 1. Forward Current Derating of Case Temperature

Figure 2. Forward Current Derating of Ambient Temperature



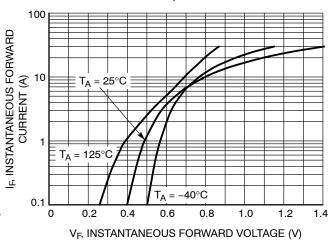


Figure 3. Typical Forward Characteristics

Figure 4. Maximum Forward Characteristics

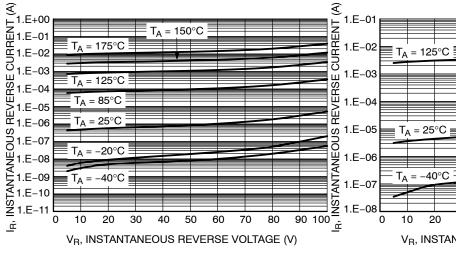


Figure 5. Typical Reverse Characteristics

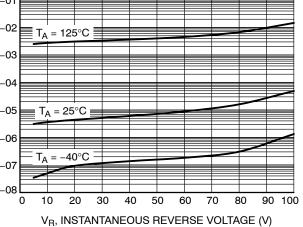


Figure 6. Maximum Reverse Characteristics

### **TYPICAL CHARACTERISTICS**

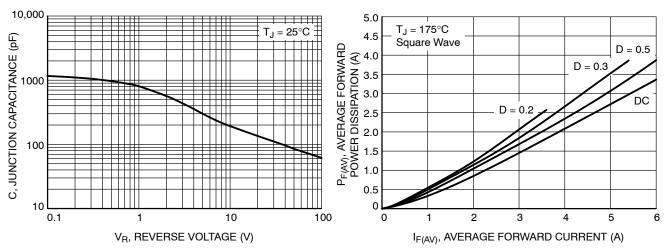


Figure 7. Typical Junction Capacitance

Figure 8. Average Forward Power Dissipation

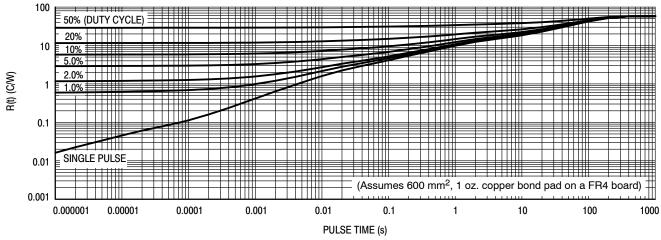


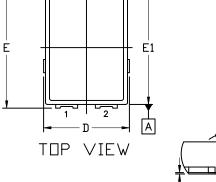
Figure 9. Typical Thermal Characteristics, Junction-to-Ambient

## **PACKAGE DIMENSIONS**

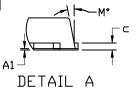
## TO-277-3LD CASE 340CZ ISSUE A

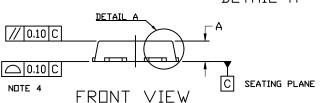
#### NOTES:

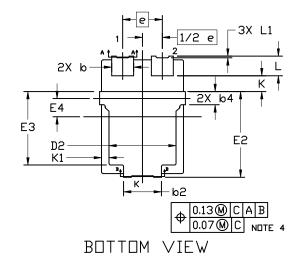
- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- DIMENSIONS 6, 61,62,63,66 AND C TO BE MEASURED ON FLAT SECTION OF THE LEAD, BETWEEN 0.13 AND 0.25mm FROM LEAD TIP.
- 4. COPLANARITY APPLES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
- 5. POSITIONAL TOLERANCE APPLIES TO THE TERMINALS AND EXPOSED PAD.
- A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
- 7. DIMENSIONS D AND E TO BE DETERMINED AT DATUM PLANE C.



D1 K B

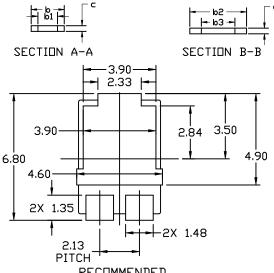






	MILLIMETERS		
DIM	MIN.	N□M.	MAX.
Α	1.00	1.10	1.20
A1		0.01	0.05
b	1.13	1.18	1.28
b1	0.70 REF		
b2	1.98	2.03	2.13
b3	1.20 REF		
b4	0.71 REF		
С	0.20 REF		
D	4.45	4.60	4.75
D1	4.35	4.40	4.45
D2	3.50	3.60	3.70

	MILLIMETERS		
DIM	MIN.	N□M.	MAX.
Ε	6.35	6.50	6.65
E1	6.05	6.10	6.15
E2	4.50	4.60	4.70
E3	3.84	3.94	4.04
E4	0.98 REF		
e	2.13 BSC		
K	0.85 REF		
K1	0.40 REF		
L	0.90	1.05	1.20
L1	0.02		
М			12*



RECOMMENDED MOUNTING FOOTPRINT

For additional information on our Pb-Free strategy and soldering details, please download the IDN Seniconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

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